BTA216B series D, E and F

GENERAL DESCRIPTION

Passivated guaranteed commutation triacs in a plastic envelope suitable for surface mounting, intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

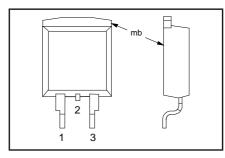
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{DRM} I _{T(RMS)} I _{TSM}	BTA216B- BTA216B- BTA216B- Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	600D 600E 600F 600 16 140	V A A

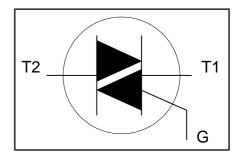
PINNING - SOT404

PIN	DESCRIPTION			
1	main terminal 1			
2	main terminal 2			
3	gate			
mb	main terminal 2			

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DRM}	Repetitive peak off-state voltages		1	600¹	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 99 °C	-	16	А
I _{TSM}	Non-repetitive peak on-state current	full sine wave; T _j = 25 °C prior to surge	_		
12.	12.	t = 20 ms t = 16.7 ms	-	140 150	A A
l²t dl _⊤ /dt	l²t for fusing Repetitive rate of rise of on-state current after	$ t = 10 \text{ ms} I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A}; dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	98 100	A ² s A/μs
I _{GM} P _{GM}	triggering Peak gate current Peak gate power		-	2 5	A W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5	W
${f T}_{ m stg} \ {f T}_{ m j}$	Storage temperature Operating junction temperature	, , , , , , , , , , , , , , , , , , , ,	-40 -	150 125	,C ,C

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¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle minimum footprint, FR4 board		- - 55	1.2 1.7 -	K/W K/W K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
		BTA216B-		D	Е	F	
I _{GT}	Gate trigger current ²	V _D = 12 V; I _T = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	5 5 5	10 10 10	25 25 25	mA mA mA
I _L	Latching current	V _D = 12 V; I _{GT} = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	15 25 25	25 30 30	30 40 40	mA mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	15	25	30	mA
			D, E, F				
V_{GT}	On-state voltage Gate trigger voltage	$I_T = 20 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$ $I_T = 125 \text{ °C}$	- - 0.25		1.5 1.5 -		>>>
I _D	Off-state leakage current	$V_D = V_{DRM(max)}$; $T_j = 125 ^{\circ}C$	-		0.5		mA

DYNAMIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		MAX.	UNIT
		BTA216B-	D	E	F		
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)};$ $T_j = 110 °C;$ exponential waveform; gate open circuit	30	60	70	-	V/μs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T_{(RMS)}} = 16 \text{ A};$ $dV_{com}/dt = 10V/\mu\text{s}; \text{ gate}$ open circuit	2.5	6.2	18	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	V_{DM} = 400 V; T_j = 125 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 0.1V/μs; gate open circuit	12	20	50	-	A/ms

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² Device does not trigger in the T2-, G+ quadrant.

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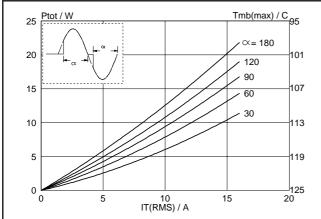


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

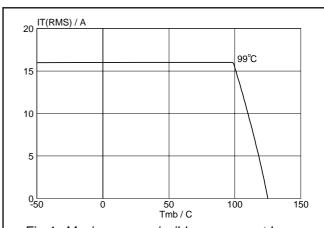


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

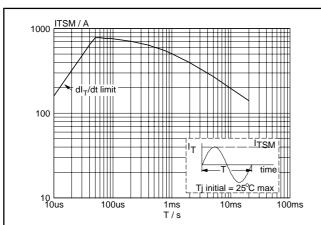


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

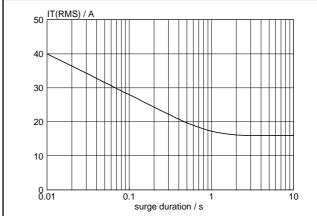


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 99$ °C.

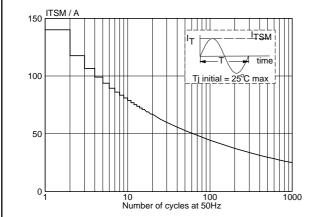


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

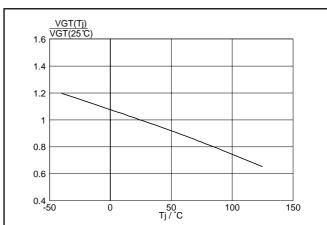
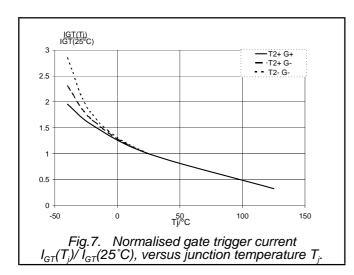
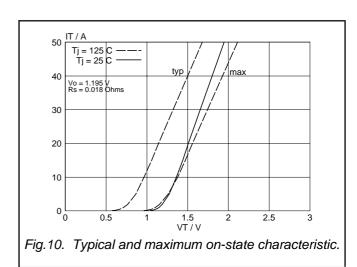
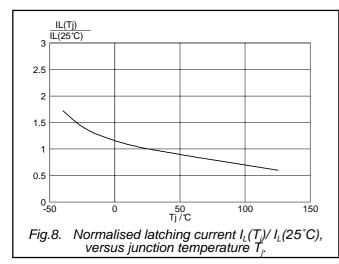


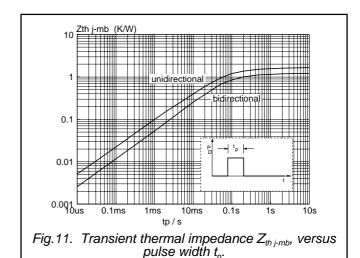
Fig.6. Normalised gate trigger voltage $V_{GT}(T_i)/V_{GT}(25^{\circ}C)$, versus junction temperature T_i .

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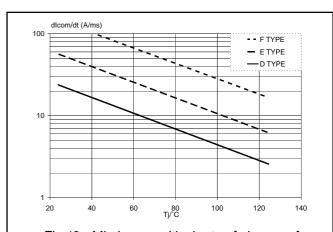
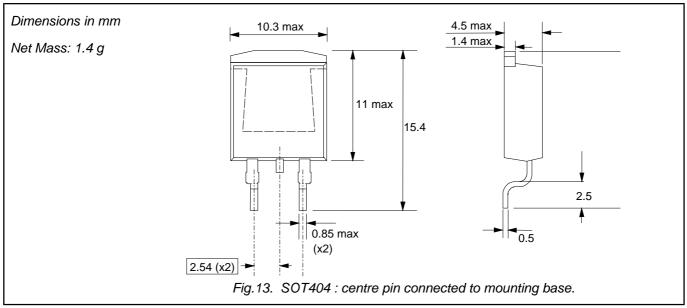


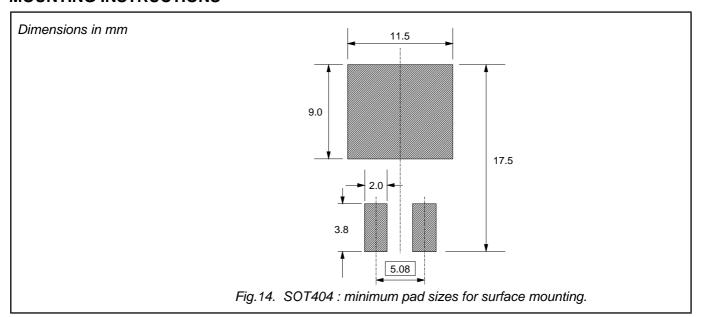
Fig.12. Mimimum, critical rate of change of commutating current dI_{com}/dt versus junction temperature, $dV_{com}/dt = 10V/\mu s$.

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MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Plastic meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Three quadrant triacs guaranteed commutation

BTA216B series D, E and F

DEFINITIONS

DATA SHEET STATUS						
DATA SHEET STATUS ³	PRODUCT STATUS ⁴	DEFINITIONS				
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice				
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product				
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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³ Please consult the most recently issued datasheet before initiating or completing a design.

⁴ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.